

ABSTRACT

A multi-layer printed wiring board comprises a first printed wiring assembly including a printed wiring board, and components mounted on a first surface of the printed wiring board, the components and first surface being covered by a layer of conformal material; and a first conductive pattern which is not part of the first printed wiring assembly, wherein the layer of conformal material is positioned between the first conductive pattern and the first printed wiring assembly. A method of forming a multi-layer printed wiring board comprises providing a first printed wiring assembly; encapsulating at least some components of the printed wiring assembly in a layer of conformal material to form an inner layer; and coupling at least one additional conductive layer to the inner layer such that the conformal layer is positioned between the at least one additional conductive layer and the printed wiring assembly.